



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Larry D. Kinsman

**Serial No.:** 10/792,229

**Filed:** March 3, 2004

**For:** BUMPED DIE AND WIRE BONDED  
BOARD-ON-CHIP PACKAGE

**Confirmation No.:** 4782

**Examiner:** T. Ho

**Group Art Unit:** 2818

**Attorney Docket No.:** 2269-4585.3US  
(00-0658.03/US)

**Notice of Allowance Mailed:**

May 8, 2006

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EV 827473173 US

Date of Deposit with USPS: August 3, 2006

Person making Deposit: Brett Hooke

**AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)**

Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the specification** begin on page 2 of this paper;

**A listing of the claims** begins on page 4 of this paper;

**Remarks** start at page 13 of this paper.

OK  
to Enter  
TH  
08/06